# MC10H171

Dual Binary to 1-4 Decoder (Low)

Description

The MC10H171 is a binary coded 2 line to dual 4 line decoder with selected outputs low. With either $\overline{E}0$ or $\overline{E}1$ high, the corresponding selected 4 outputs are high. The common enable $\overline{E}$, when high, forces all outputs high.

Features

- Propagation Delay, 2 ns Typical
- Power Dissipation 325 mW Typical (same as MECL 10K™)
- Improved Noise Margin 150 mV (over operating voltage and temperature range)
- Voltage Compensated
- MECL 10K Compatible
- Pb−Free Packages are Available*

LOGIC DIAGRAM

V_{CC1} = PIN 1
V_{CC2} = PIN 16
V_{EE} = PIN 8

**DIP
PIN ASSIGNMENT**
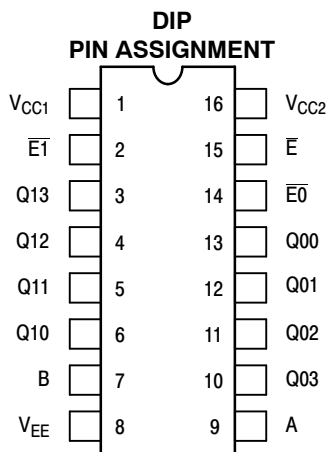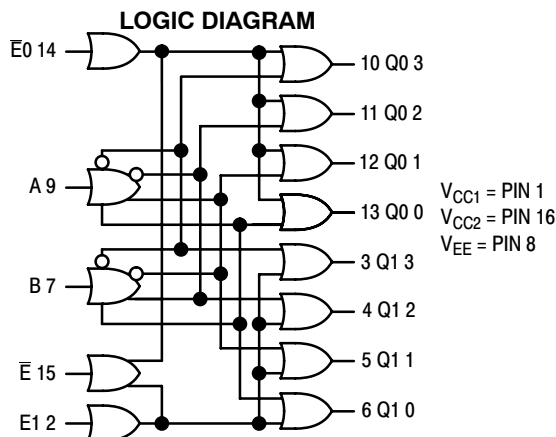
Pin assignment is for Dual−in−Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18
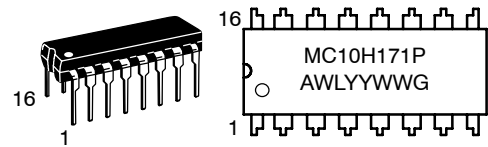of the ON Semiconductor MECL Data Book (DL122/D).

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.
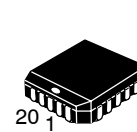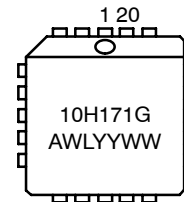
ON Semiconductor®

MARKING DIAGRAMS*

**PDIP−16
P SUFFIX
CASE 648**

MC10H171P
AWLYYWWG

**PLLC−20
FN SUFFIX
CASE 775**

10H171G
AWLYYWW

A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb−Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

March, 2006 − Rev. 7

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Table 1. MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V_{EE}	Power Supply (V_{CC} = 0)	−8 to 0	Vdc
V_I	Input Voltage (V_{CC} = 0)	0 to V_{EE}	Vdc
I_{out}	Output Current – Continuous – Surge	50 100	mA
T_A	Operating Temperature Range	0 to +75	°C
T_{stg}	Storage Temperature Range – Plastic – Ceramic	−55 to +150 −55 to +165	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 2. ELECTRICAL CHARACTERISTICS (V_{EE} = −5.2 V ±5%) (Note 1)

Symbol	Characteristic	0° Min	0° Max	25° Min	25° Max	75° Min	75° Max	Unit
I_E	Power Supply Current	–	85	–	77	–	85	mA
I_{inH}	Input Current High	–	425	–	265	–	265	μA
I_{inL}	Input Current Low	0.5	–	0.5	–	0.3	–	μA
V_{OH}	High Output Voltage	−1.02	−0.84	−0.98	−0.81	−0.92	−0.735	Vdc
V_{OL}	Low Output Voltage	−1.95	−1.63	−1.95	−1.63	−1.95	−1.60	Vdc
V_{IH}	High Input Voltage	−1.17	−0.84	−1.13	−0.81	−1.07	−0.735	Vdc
V_{IL}	Low Input Voltage	−1.95	−1.48	−1.95	−1.48	−1.95	−1.45	Vdc

1. Each MECL 10H™ series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50 Ω resistor to −2.0 V.

Table 3. AC PARAMETERS

Symbol	Characteristic	0° Min	0° Max	25° Min	25° Max	75° Min	75° Max	Unit
t_{pd}	Propagation Delay Data Select	 0.5 0.5	 2.0 2.6	 0.5 0.5	 2.1 2.7	 0.5 0.5	 2.2 2.8	ns
t_r	Rise Time	0.5	1.7	0.5	1.8	0.5	1.9	ns
t_f	Fall Time	0.5	1.7	0.5	1.8	0.5	1.9	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

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Table 4. TRUTH TABLE

Enable Inputs			Inputs		Outputs							
$\overline{E}$	$\overline{E}0$	$\overline{E}1$	A	B	Q10	Q11	Q12	Q13	Q00	Q01	Q02	Q03
L	L	L	L	L	L	H	H	H	L	H	H	H
L	L	L	L	H	H	L	H	H	H	L	H	H
L	L	L	H	L	H	H	L	H	H	H	L	H
L	L	L	H	H	H	H	H	L	H	H	H	L
L	L	H	L	L	H	H	H	H	L	H	H	H
L	H	L	L	L	L	H	H	H	H	H	H	H
H	X	X	X	X	H	H	H	H	H	H	H	H

ORDERING INFORMATION

Device	Package	Shipping[†]
MC10H171FN	PLLC–20	46 Units / Rail
MC10H171FNG	PLLC–20 (Pb–Free)	46 Units / Rail
MC10H171P	PDIP–16	25 Unit / Rail
MC10H171PG	PDIP–16 (Pb–Free)	25 Unit / Rail

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

20 LEAD PLLC
CASE 775–02
ISSUE E

VIEW D–D

VIEW S

VIEW S

SEATING PLANE

NOTES:
1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
2. DIMENSIONS IN INCHES.
3. DATUMS –L–, –M–, AND –N– DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM –T–, SEATING PLANE.
5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2 °	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

PACKAGE DIMENSIONS

PDIP−16
P SUFFIX
PLASTIC DIP PACKAGE
CASE 648−08
ISSUE R
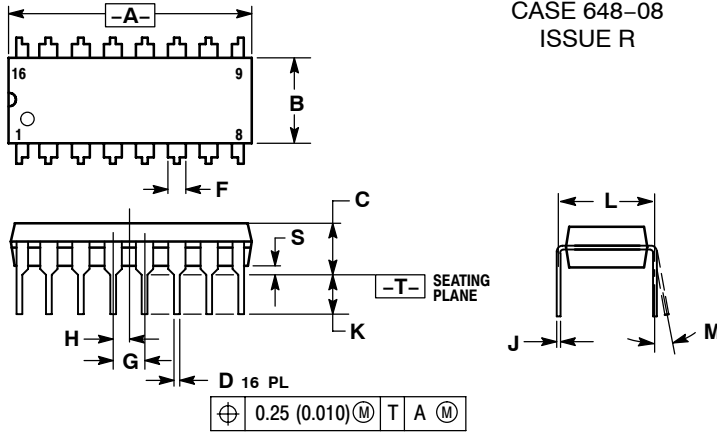
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

⊕ | 0.25 (0.010) Ⓜ | T | A Ⓜ

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